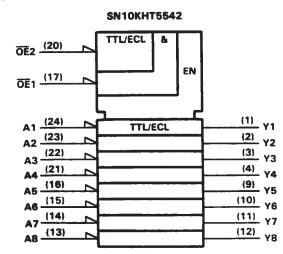
SDZS001A - D3136, AUGUST 1988 - REVISED DECEMBER 1988

- 10KH Compatible
- ECL and TTL Control Inputs
- P-N-P Inputs Reduce DC Loading
- Flow-Through Architectures Optimizes PCB Layout
- Center Pin V<sub>CC</sub>, V<sub>EE</sub> and GND Configurations Minimize High-Speed Switching Noise
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015
- Package Options Include "Small Outline" Packages and Standard Plastic 300-mil DIPs

### description

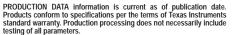
These octal TTL-to-ECL translators are designed to provide efficient translation between a TTL signal environment and a 10KH ECL signal environment. The designer has a choice of inverting ('5542) or true ('5543) outputs. Two pins,  $\overline{OE1}$  and  $\overline{OE2}$ , are provided for output enable control. These control inputs are negative ANDed together, with  $\overline{OE1}$  being ECL compatible and  $\overline{OE2}$  being TTL compatible. This offers the choice of controlling the outputs of the device from either a TTL or ECL signal environment. The outputs, when disabled, go to a normal ECL logic low level.

The SN10KHT5542 and SN10KHT5543 are characterized for operation from 0°C to 75°C.



## logic symbols<sup>†</sup>

<sup>†</sup>These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

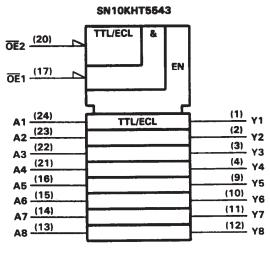




DW OR NT PACKAGE (TOP VIEW)								
Y1 Y2 Y3 GND GND GND GND Y5 Y6 Y7 Y8		U 24 23 22 21 20 19 18 17 16 0 15 14 2 13		VCC V <sub>EE</sub>	(TTL) (ECL)			

### FUNCTION TABLE

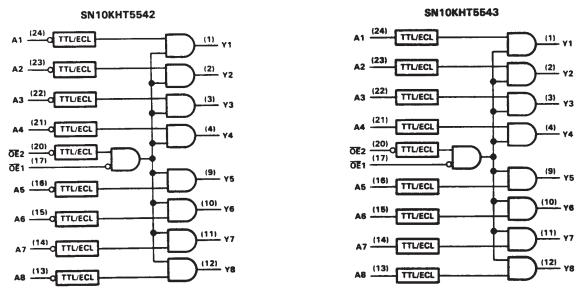
	'PUT TROL	DATA INPUT	OUTPUT			
OE1	OE2	Α	'5542	'5543		
н	X	X	L	L		
X	н	X	L	L		
L	L	L	н	L		
L	L	н	LH			



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## logic diagrams (positive logic)



absolute maximum ratings over operating ambient temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, VCC	$\dots$ -0.5 V to 7 V
Supply voltage range, VEE	8 V to 0 V
Input voltage range (TTL) (See Note 1)	– 1.2 V to 7 V
Input voltage range (ECL)	
Input current range (TTL)	-30 mA to 5 mA
Operating ambient temperature range	0°C to 75°C
Storage temperature range	-65°C to 150°C

<sup>†</sup>Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

## recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
Vcc	TTL supply voltage		4.5	5.0	5.5	V
VEE	ECL supply voltage			-5.2	- 5.46	V
VIH	TTL high-level input voltage					V
		0°C	-1170		-840	
VIH	ECL high-level input voltage <sup>‡</sup>	25°C	-1130		-810	mV
. 111		75°C	- 1070		- 735	
VIL	TTL low-level input voltage				0.8	V
		0°C	- 1950	-	- 1480	
VIL	ECL low-level input voltage <sup>‡</sup>	25°C	- 1950	-	- 1480	mV
- 16	•	75°C	- 1950	-	- 1450	]
ЧК	TTL input clamp current		1		- 18	mA
TA	Operating ambient temperature (see Note 3)		0		75	°C

<sup>‡</sup> The algebraic convention, in which the least positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels and temperature only.

NOTES: 2. If unused,  $\overline{OE1}$  should be tied directly to -2 V.

3: Each 10KH series circuit has been designed to meet the dc specifications shown in the electrical characteristics table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board, and transverse air flow greater than 500 linear ft/min is maintained.



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### electrical characteristics over recommended operating ambient temperature range (unless otherwise noted) (see Note 2)

	PARAMETER		TEST CONDITIONS		MIN	TYP <sup>†</sup> MAX	UNIT
VIK	A inputs and OE2	$V_{CC} = 4.5 V,$	$V_{EE} = -4.94 V$ , $i_{I} = -18 mA$			-1.2	V
1	A inputs and OE2	$V_{CC} = 5.5 V,$	$V_{EE} = -5.46 \text{ V}, \text{ V}_{I} = 7 \text{ V}$			0.1	mA
	A inputs and OE2	$V_{CC} = 5.5 V,$	$V_{EE} = -5.46 \text{ V}, \text{ V}_{I} = 2.7 \text{ V}$			20	
1		$V_{CC} = 5.5 V,$	$V_{EE} = -5.46 \text{ V}, \text{ V}_{I} = -840 \text{ mV}$	0°C		350	Α
ЧH	OE1 only	$V_{CC} = 5.5 V,$	$V_{EE} = -5.46 \text{ V}, \text{ V}_{I} = -810 \text{ mV}$	25°C		350	] ///
		$V_{CC} = 5.5 V,$	$V_{EE} = -5.46 \text{ V}, \text{ V}_{I} = -735 \text{ mV}$	75°C		350	
	A inputs and OE2	$V_{CC} = 5.5 V,$	$V_{EE} = -5.46 \text{ V},  V_{I} = 0.5 \text{ V}$			- 500	
				0°C	0.5		Α
μL	OE1 only	$V_{\rm CC} = 5.5 V,$	$V_{EE} = -5.46 V, V_{I} = -1950 mV$	25°C	0.5		<u> </u>
				75°C 0.5	0.5		
	• · · · · · · · · · · · · · · · · · · ·			0°C	- 1020	- 840	
VOH <sup>‡</sup>	;	$V_{CC} = 4.5 V,$	$V_{EE} = -5.2 V, \pm 5\%$ , See Note 3	25°C	- 980	-810	mV
				75°C	-920	- 735	
				0°C	- 1950	- 1630	
VOL <sup>‡</sup>		$V_{CC} = 4.5 V,$	VEE = -5.2 V, ±5%, See Note 3	25 °C	- 1950	- 1630	m∨
				75°C	- 1950	- 1600	]
ІССН		$V_{CC} = 5.5 V$ ,	$V_{EE} = -5.46 V$			15 22	mA
ICCL		$V_{CC} = 5.5 V,$	VEE = -5.46 V			17 25	mA
IEE		$V_{CC} = 5.5 V,$	$V_{EE} = -5.46 V$			-78 -111	mA
Ci		$V_{CC} = 5 V$ ,	$V_{EE} = -5.2 V$ , f = 10 MHz			5	pF

switching characteristics over recommended ranges of operating ambient temperature and supply voltage (unless otherwise noted) (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP <sup>†</sup>	MAX	UNIT		
tplh	A	×	0.1	1.7	3.7			
tPHL	Any A	T	0.1	1.6	3.3	ns		
tPLH	OE1 (ECL)	×	0.8	2.8	5	5 4.5		
<sup>t</sup> PHL		Ť	0.4	2.3	4.5			
tPLH		Y	0.8	3	5.3	ns		
<sup>t</sup> PHL		Y	0.6	2.5	4.7			
t <sub>r</sub>				1.1		1.5		
tf	1	T T		1.5	ns			

<sup>†</sup> All typical values are at  $V_{CC} = 5 V$ ,  $V_{EE} = -5.2 V$ ,  $T_A = 25 °C$ . <sup>‡</sup> The algebraic convention, in which the least positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels and temperature only.

NOTES: 2. Each 10KH series circuit has been designed to meet the dc specifications shown in the electrical characteristics table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear ft/min is maintained.

3. Outputs are terminated through a 50- $\Omega$  resistor to -2 V.

4. Load circuit and switching waveforms are shown in Section 1.



SDZS001A - D3136, AUGUST 1988 - REVISED DECEMBER 1988

# electrical characteristics over recommended operating ambient temperature range (unless otherwise noted) (see Note 2)

	PARAMETER		TEST CONDITI	ONS		MIN	TYP <sup>†</sup>	MAX	UNIT
VIK	A inputs and OE2	$V_{CC} = 4.5 V,$	$V_{EE} = -4.94 V,$	$I_{ } = -18 \text{ mA}$				-1.2	V
1	A inputs and OE2	$V_{CC} = 5.5 V,$	$V_{EE} = -5.46 V_{,}$	V <sub>I</sub> = 7 V				0.1	mA
	A inputs and OE2	$V_{CC} = 5.5 V,$	$V_{EE} = -5.46 V,$	V <sub>1</sub> = 2.7 V				20	
		$V_{\rm CC} = 5.5 V,$	$V_{EE} = -5.46 V_{,}$	$V_{I} = -840 \text{ mV}$	0°C			350	Aµ
ЧΗ	OE1 only	$V_{\rm CC} = 5.5 V_{\rm c}$	$V_{EE} = -5.46 V,$	$V_{l} = -810 \text{ mV}$	25 °C			350	part -
		$V_{CC} = 5.5 V_{c}$	$V_{EE} = -5.46 V,$	$V_{ } = -735 \text{ mV}$	75°C			350	
	A inputs and OE2	$V_{CC} = 5.5 V_{,}$	$V_{EE} = -5.46 V_{,}$	$V_{1} = 0.5 V$				- 500	
					0°C	0.5			μA
	OE1 only	E1 only $V_{CC} = 5.5 V$ ,	$V_{EE} = -5.46 V$ , $V_{I} = -1950 mV_{I}$			0.5			
					0°C	- 1020		- 840	
Voн‡		$V_{CC} = 4.5 V.$	$V_{EE} = -5.2 V, \pm$	5%, See Note 3	25 °C	- 980		-810	mV
					75°C	- 920		-735	
					0°C	- 1950	-	1630	
VoL‡		$V_{CC} = 4.5 V,$	$V_{EE} = -5.2 V, \pm$	5%, See Note 3	25°C	- 1950	-	1630	mV
					75°C	- 1950	-	1600	
ІССН		$V_{CC} = 5.5 V,$	VEE = -5.46 V				17	25	mA
ICCL		$V_{CC} = 5.5 V_{,}$	VEE = -5.46 V				15	22	mA
IEE		$V_{CC} = 5.5 V$ ,	$V_{EE} = -5.46 V$				-7 <b>7</b>	-111	mA
Ci		$V_{CC} = 5 V$ .	$V_{EE} = -5.2 V,$	f = 10 MHz	_		5		pF

switching characteristics over recommended ranges of operating ambient temperature and supply voltage (unless otherwise noted) (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYPT	MAX	UNIT
<sup>t</sup> PLH		V	0.1	1.5	3	-
tPHL	Any A	T	0.1	1.5	3.3	ns
tPLH		v	0.6	2.2	4.3	—ins i
tPHL	OE1 (ECL)	Y	0.5	2.4	4.3	
tPLH		V	0.7	2.2	4.4	ns
tPHL	OE2 (TTL)	Y	0.5	2.6	4.7	
te		~		1.5		ns
te	1	Y		1.5		

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, V<sub>EE</sub> = -5.2 V, T<sub>A</sub> = 25 °C.

<sup>+</sup> The algebraic convention, in which the least positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels and temperature only.

NOTES: 2. Each 10KH series circuit has been designed to meet the dc specifications shown in the electrical characteristics table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear ft/min is maintained.

3. Outputs are terminated through a 50- $\Omega$  resistor to -2 V.

4. Load circuit and voltage waveforms are shown in Section 1.



## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN10KHT5542DW	ACTIVE	SOIC	DW	24	25	TBD	Call TI	Call TI
SN10KHT5542DWE4	ACTIVE	SOIC	DW	24	25	TBD	Call TI	Call TI
SN10KHT5542DWG4	ACTIVE	SOIC	DW	24	25	TBD	Call TI	Call TI
SN10KHT5542DWR	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI
SN10KHT5542NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN10KHT5542NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN10KHT5543DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN10KHT5543DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN10KHT5543DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN10KHT5543DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN10KHT5543NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN10KHT5543NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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\*A

Pin1 Quadrant

Q1

## TAPE AND REEL INFORMATION





# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



All dimensions are nominal												
Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	1
SN10KHT5543DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	



# PACKAGE MATERIALS INFORMATION

11-Mar-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN10KHT5543DWR	SOIC	DW	24	2000	346.0	346.0	41.0

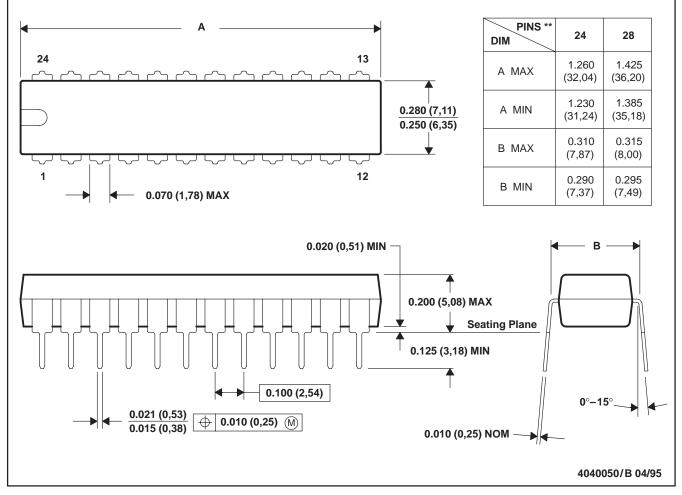
# **MECHANICAL DATA**

MPDI004 - OCTOBER 1994

## NT (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters). B. This drawing is subject to change without notice.



DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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